

RV1S9960A

R08DS0169EJ0200 Rev.2.00 Jun. 30, 2021

HIGH CMR, 15Mbps CMOS OUTPUT, LOW FORWARD-CURRENT(IF) 3.3V/5V OPERATION, 15 mm LONG-CREEPAGE 8-PIN LSDIP

DESCRIPTION

The RV1S9960A is a photocoupler featuring high-speed switching up to 15Mbps with active low output logic which consist of an AlGaAs LED on the input side and an integrated circuit with a photodiode on the output.

This product enables to low current operation on 3.3V/5V power supply with high noise-tolerant CMR:50kV/us min. and high temperature operation up to $T_A = 110^{\circ}$ C in logic interface circuit.

FEATURES

- Long creepage distance (15 mm MIN)
- High speed communication (15 Mbps)
- High temperature operation (-40 to +110 °C)
- High common mode (dv/dt) tolerant (CM_H, CM_L = \pm 50 kV/ μ s MIN.)
- High isolation voltage (BV = 7 500 Vr.m.s.)
- Low input drive current (IFHL = 3.8 mA MAX.)
- Low voltage power supply operation (V_{DD} = 2.7 V ~ 5.5 V)
- Low pulse width distortion (PWD = 20 ns MAX.)
- Ordering number of tape product :

RV1S9960ACCSP-10Yx#KC0: 1 000 pcs/reel

- Pb free product
- · Safety standards approval

UL: UL1577, Double protection

CSA: CAN/CSA-C22.2 No.62368-1, Reinforced insulation

VDE: DIN EN 60747-5-5 (Option)

PIN CONNECTION (Top View) 8 7 6 5 2. Anode 3. Cathode 4. NC 5. GND 6. Vo 7. NC 8. VDD

TRUTH TABLE

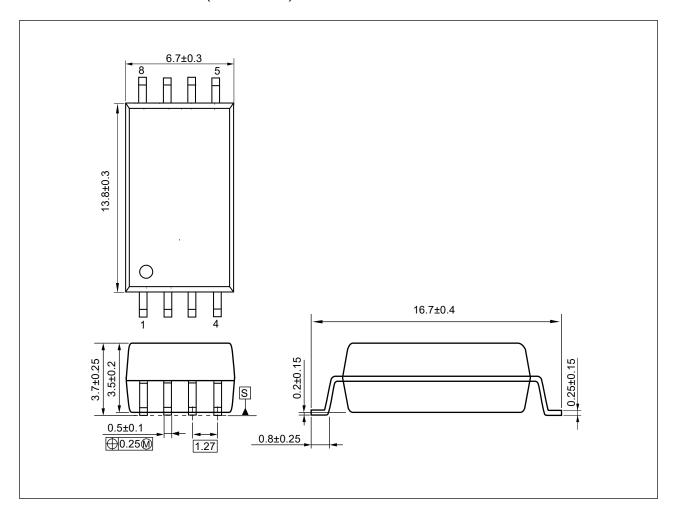
LED	OUTPUT
ON	L
OFF	Н

APPLICATIONS

- Industrial Inverter
- Solar Inverter
- Power Conditioner

Start of mass production Jun.2019

PACKAGE DIMENSIONS (UNIT: mm)

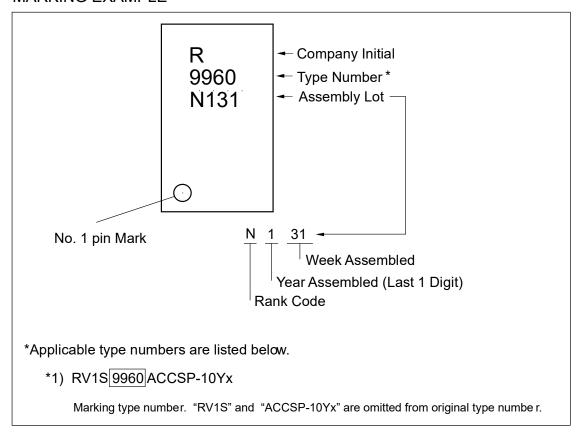


Weight: 0.642g (typ.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	14.5 mm
Creepage Distance	15 mm
Isolation Distance	0.4 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating	Packing Style	Safety Standard	Application
		Specification		Approval	Part Number*1
RV1S9960ACCSP-	RV1S9960ACCSP	Pb-Free and	10 pcs	Standard products	RV1S9960A
10YC	-10YC#SC0	Halogen Free	(Tape 10 pcs cut)	(UL, CSA approved)	
	RV1S9960ACCSP	(Ni/Pd/Au)	Embossed Tape 1 000		
	-10YC#KC0		pcs/reel		
RV1S9960ACCSP-	RV1S9960ACCSP		10 pcs	UL, CSA,	
10YV	-10YV#SC0		(Tape 10 pcs cut)	DIN EN 60747-5-5	
	RV1S9960ACCSP		Embossed Tape 1 000	approved	
	-10YV#KC0		pcs/reel		

Notes: *1. For the application of the Safety Standard, following part number should be used.

ABSOLUTELY MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	lF	20	mA
	Reverse Voltage	VR	5	V
Detector	Supply Voltage	V_{DD}	6	V
	Output Voltage	Vo	6	V
	Output Current	lo	10	mA
	Power Dissipation *1	Pc	250	mW
Isolation Voltage*2		BV	7 500	Vr.m.s.
Operating Ambient Temperature		TA	-40 to +110	°C
Storage Temperature		T _{stg}	-55 to +125	°C

Notes: 1. Reduced to 5.0 mW/°C at T_A = 85 °C or more

2. AC Voltage for 1minite at T_A = 25 °C, RH = 60 % between input and output. Pins 1-4 shorted together, 5-8 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Low Level forward voltage	V _{FL}	0		8.0	V
High Level Forward Current	I _{FH}	5		8	mA
Supply Voltage	V_{DD}	2.7		5.5	V

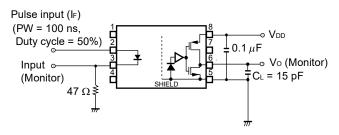
ELECTRICAL CHARACTERISTICS

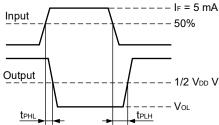
(T_A = - 40 to +110 °C, V_{DD} = 2.7 to 5.5 V, unless otherwise specified)

	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 6 mA, T _A = 25 °C	1.4	1.55	1.7	V
	Reverse Current	I _R	V _R = 3 V, T _A = 25 °C			10	μΑ
	Terminal Capacitance	Ct	V _F = 0 V, f = 1 MHz, T _A = 25 °C		30		pF
Detector	High Level Output Current	IDDH	I _F = 0 mA		1.1	2	mA
	Low Level Output Current	I _{DDL}	I _F = 5 mA		1.0	2	
	High Level Output Voltage	Vон	$I_0 = -3.2 \text{ mA}, I_F = 0 \text{ mA}$	V _{DD} -1.0	V _{DD}		V
			$I_0 = -20 \mu A, I_F = 0 mA$	V _{DD} -0.1	V _{DD}		
	Low Level Output Voltage	Vol	$I_0 = 3.2 \text{ mA}, I_F = 5 \text{ mA}$		0.13	0.4	
			$I_0 = 20 \mu\text{A}, I_F = 5 \text{mA}$		0.001	0.1	
Coupled	Threshold Input Voltage (H to L)	IFHL	Vo < 0.4 V		1.8	3.8	mA
	Isolation Resistance	R _{I-O}	$V_{I-O} = 1 \text{ kV}_{DC}$, RH = 40 to 60 %,	10 ¹¹			Ω
			T _A = 25 °C				
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25 °C		0.6		pF
	Propagation Delay Time	t _{PHL}	$I_F = 5 \text{ mA} \Leftrightarrow 0 \text{ mA}$		36	60	ns
	(H to L)*2		V _{DD} = 3.3 V,5 V				
	Propagation Delay Time (L to H)*2	tplH	C _L = 15 pF		38	60	
	Pulse Width Distortion*2	PWD			2	20	
	Propagation Delay Skew	t _{PSK}				25	
	Rise Time	tr			5		
	Fall Time	t _f			5		
	Common Mode	[СМн]	$I_F = 0 \text{ mA}, V_O > 4 \text{ V(V}_{DD} = 5 \text{ V)},$	50	60		kV/μs
	Transient Immunity at		$V_0 > 2.3 \text{ V}(V_{DD} = 3.3 \text{ V}),$				
	High Level Output*3		V _{CM} = 1.5 kV, T _A = 25 °C				
	Common Mode	CM _L	I _F = 5 mA,	50	60		
	Transient Immunity at		$V_O < 0.4 \text{ V(V}_{DD} = 3.3 \text{ V, 5 V)},$				
	Low Level Output*3		V _{CM} = 1.5 kV, T _A = 25 °C				

Note2: 1. Typical values at T_A = 25 °C

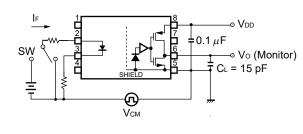
2. Test circuit for propagation delay time measurement

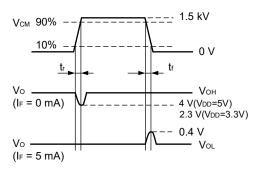




Remark C_L includes probe and stray wiring capacitance.

3. Test circuit for common mode transient immunity measurement



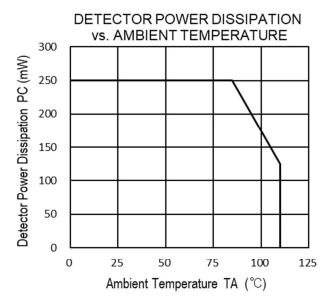


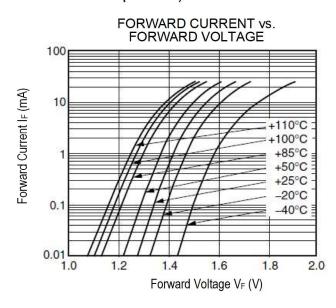
 $\label{eq:closed} \textbf{Remark} \qquad C_L \text{ includes probe and stray wiring capacitance}.$

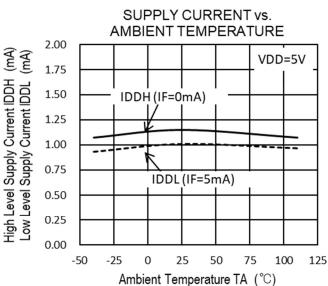
USAGE CAUTIONS

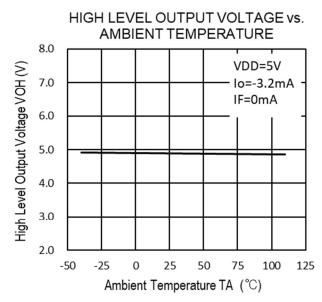
- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- **2.** By-pass capacitor of more than 0.1 μ F is used between V_{DD} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Pin 1, 4 (which is an NC*1 pin) can either be connected directly to the GND pin on the LED side or left open. Also, Pin 7 (which is an NC*1 pin) can either be connected directly to the GND pin on the detector side or left open.
 - Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.
 - Note: *1. NC: Non-Connection (No Connection).
- 4. Avoid storage at a high temperature and high humidity.

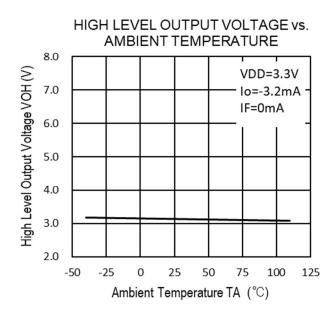
TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

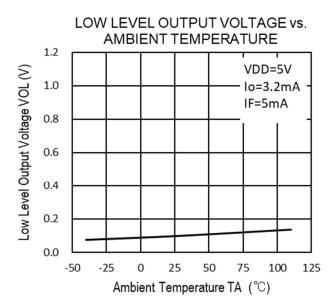




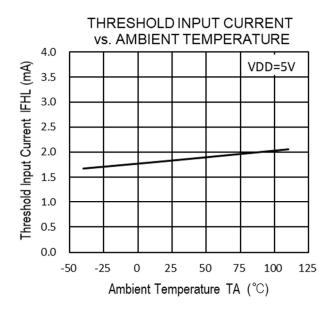


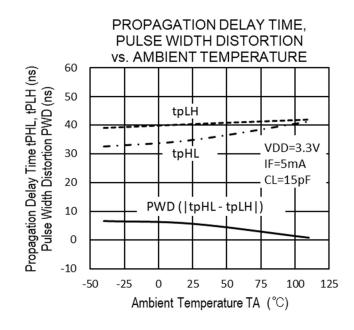


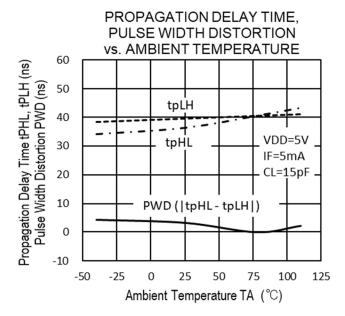


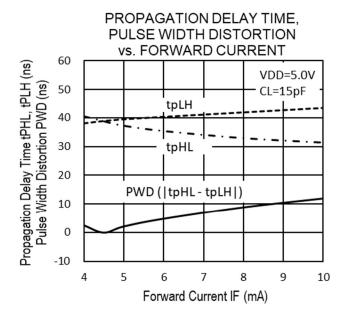


Remark The graphs indicate nominal characteristics.



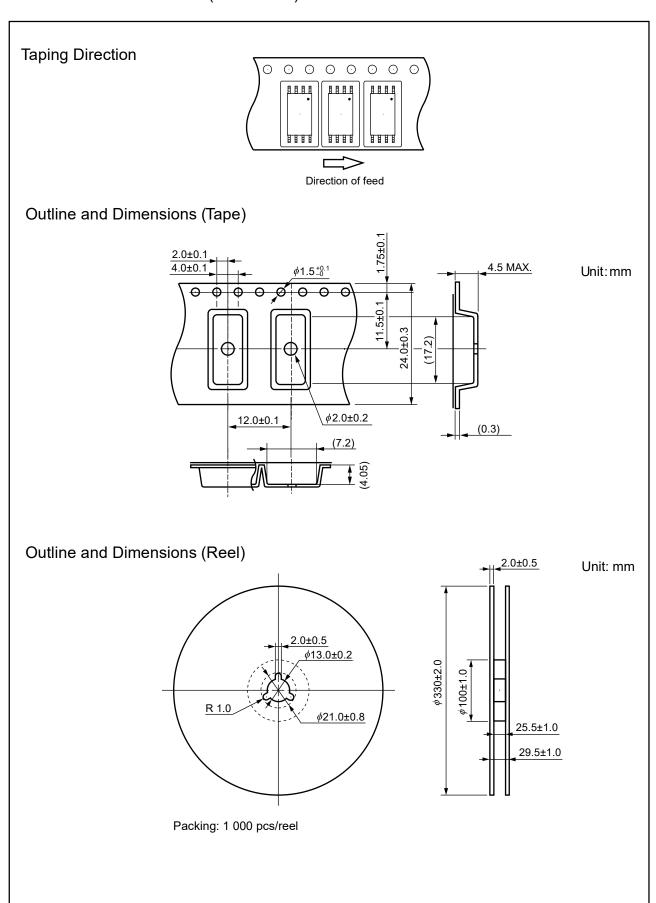




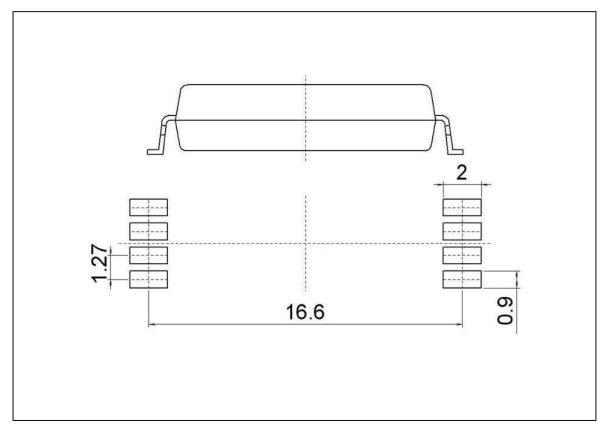


Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



[8pin LSDIP]

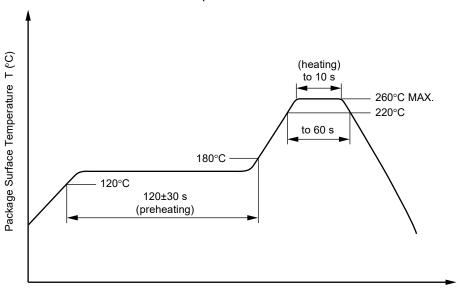
Remark All dimensions in this figure must be evaluated before use.

NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering
 - Peak reflow temperature
 260 °C or below (package surface temperature)
 - Time of peak reflow temperature
 Time of temperature higher than 220 °C
 10 seconds or less
 60 seconds or less
 - Time to preheat temperature from 120 to 180 °C $\,$ 120 \pm 30 s
 - Time to preneat temperature from 120 to 180 $^{\circ}$ C = 120 \pm 30
 - Number of reflows ThreeFlux Rosin

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260 °C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120 °C or below (package surface temperature)

Number of times
 Flux
 One (Allowed to be dipped in solder including plastic mold portion.)
 Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

Peak Temperature (lead part temperature)
 Time (each pins)
 350 °C or below
 3 seconds or less

• Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 110 °C

(4) Cautions

Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

• Do not use adhesives or coating materials including halogens to fix this device.

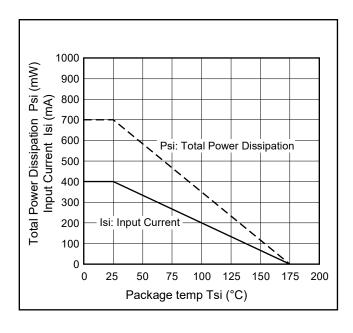
2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{DD} -GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

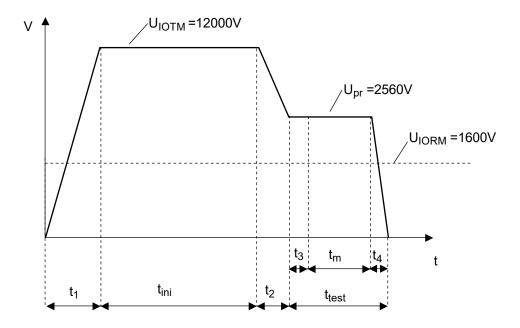
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/110/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{\text{IORM}}, P_{\text{d}} < 5 \text{pC}$	Uiorm Upr	1 600 2 560	V _{peak} V _{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr}=1.875\times U_{IORM},P_d<5\;pC$	U_pr	3 000	V_{peak}
Highest permissible overvoltage	U _{ІОТМ}	12 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	СТІ	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	Tstg	-55 to +125	°C
Operating temperature range	TA	-40 to +110	°C
Isolation resistance, minimum value VIO = 500 V dc at TA = 25°C VIO = 500 V dc at TA MAX. at least 100°C	Ris MIN. Ris MIN.	10 ¹² 10 ¹¹	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I _F , Psi = 0) Power (output or total power dissipation) Isolation resistance	Tsi Isi Psi	175 400 700	°C mA mW
V _{IO} = 500 V dc at T _A = Tsi	Ris MIN.	10 ⁹	Ω

Dependence of maximum safety ratings with package temperature



Method a Destructive Test, Type and Sample Test



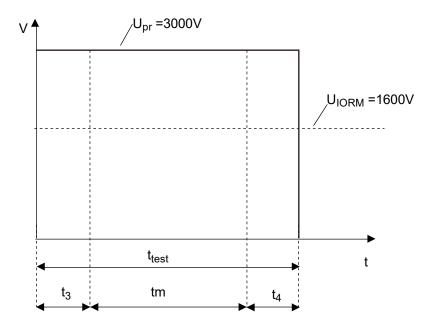
 $t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

 $t_3, t_4 = 1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 10 sec t_{test} = 12 sec

 $t_{ini} = 60 \text{ sec}$

Non-destructive Test, 100% Production Test Method b



 $t_3, t_4 = 0.1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 1.0 sec

 $t_{test} = 1.2 sec$

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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